

**ECSE-2210 Microelectronics Technology**  
**Class Activity 30**

1. a. Find the threshold voltage for a Si n-channel MOS transistor with  $N_A = 10^{17} \text{ cm}^{-3}$ ,  $\Phi_{\text{ms}} = -0.95 \text{ eV}$ ,  $Q_i = 10^{11} q / \text{cm}^2$ , and a  $\text{SiO}_2$  thickness  $d = 200 \text{ \AA}$ . **Hint:** First calculate  $V_{\text{FB}}$ . Add this to  $V_{\text{T}}'$  (= threshold value for the ideal case) to get the actual  $V_{\text{T}}$ .
  
- b. Repeat the above for a p-channel device ( $N_D = 10^{17} \text{ cm}^{-3}$ ) with the same material parameters, except  $\Phi_{\text{ms}}$ .  $\Phi_{\text{ms}}$  for this case can be calculated from the change in  $E_{\text{F}}$  compared to that of part (a).
  
- c. Plot qualitatively the  $C$ - $V$  curves for the above two MOS capacitors at high frequency. Mark important points in the curves. Specifically, show the effect of  $V_{\text{FB}}$ . (Ignore the presence of source and drain for this problem).

- d. Find the dose of boron (ions/cm<sup>2</sup>) required to change the threshold voltage of the above n-channel device to + 1 V. Assume that the implanted boron resides just below the Si surface and all impurities are ionized. Is this an enhancement mode device or a depletion mode device?
- e. Find the dose of (**boron or phosphorus: choose one**) required to change the threshold voltage of the above p-channel device to – 1 V. Assume that the implanted ions reside just below the Si surface. Is this an enhancement mode device or a depletion mode device?